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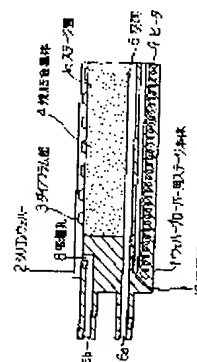
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(54) STAGE FOR SEMICONDUCTOR WAFER PROBER

(57)Abstract:

PURPOSE: To make it possible to measure the pressure sensitivity characteristic of a semiconductor pressure sensor in a wafer state, by providing a porous sintered metal body having air holes communicated to the cavity of the main body of a stage, a sucking hole for sucking the surface of a wafer, and a temperature control mechanism.

CONSTITUTION: When the pressure sensitivity characteristic of a semiconductor pressure sensor is measured, a silicon wafer 2, on which circuits and diaphragms are formed, is mounted on a stage surface 1a. A diaphragm part 3 thereof is aligned with a sintered metal body 4. When evacuation is performed through a cavity 5, a vacuum pressure is supplied to the diaphragm part 3 through the sintered metal body 4 having countless air holes. The silicon wafer 2 is fixed to the stage surface 1a by the evacuation through a sucking hole 8. The temperature of the stage surface 1a is adjusted by current conduction to a heater 9 or by sending refrigerant into a cooling pipe 10. Thus the pressure sensitivity of the semiconductor pressure sensor is measured. the pressure sensitivity characteristic of the semiconductor pressure sensor can be measured in a wafer state without separating the semiconductor wafer into chips and without assembling stems.



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